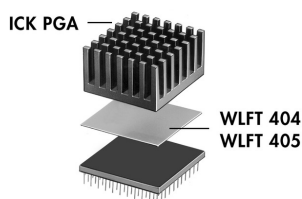


Data sheet Product ICK PGA 25 x 25

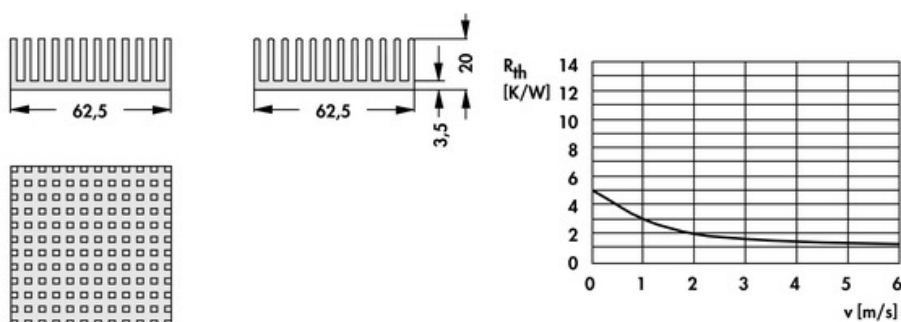


Heatsinks and active heatsinks for processors>Heatsinks for PGA
 62.5 x 62.5 x 20 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	62.5 mm
height:	20 mm
plate thickness:	3.5 mm
length:	62.5 mm
thermal resistance:	5 - 1.1 K/W
dissipation loss:	11.1 W
surface:	black anodised

Technical Drawing



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